

## Patent Abstracts of Japan

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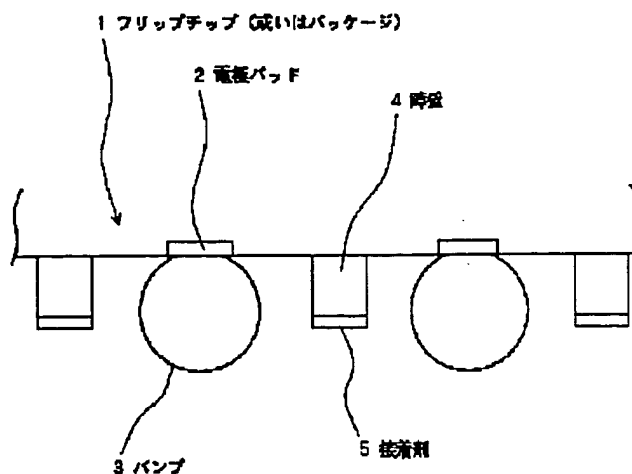
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TITLE : SEMICONDUCTOR DEVICE,  
MOUNTING METHOD OF  
SEMICONDUCTOR DEVICE AND  
MANUFACTURE THEREOF



ABSTRACT : PROBLEM TO BE SOLVED: To provide a semiconductor device on which a mounting operation can be performed easily by collective reflow, the generation of a defective article can be suppressed when mounting, mounting reliability can be enhanced and productivity can be increased.

SOLUTION: This semiconductor device is mounted on a mounting substrate using bumps. Between solder bumps 3 welded to a plurality of electrode pads 2 of a flip chip (or package) 1, is partitioned by a barrier 4 in such a manner that the barrier 4 is provided separately from the solder bumps 3, and a thermoplastic adhesive layer 5 is formed on a part or on the whole surface opposing to the mounting substrate of the barrier 4.

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